

Date: 2024-11-25

IC: 25657-SG13R

Dear Sir/Madam,

We, Guangzhou BDE Technology Inc. Hereby declares the following statement for Innovation, Science and Economic Development for the models/HVINS mentioned as below:

Product name: BDE Multi-Protocol Sub-1GHz Wireless Module

Models: BDE-SG1314R10U32,

BDE-SG1314R10N32,

BDE-SG1314R10U0,

BDE-SG1314R10N0,

BDE-SG1314R10U32-IN

BDE-SG1314R10N32-IN

BDE-SG1314R10U0-IN

BDE-SG1314R10N0-IN

BDE-SG1312R7U32,

BDE-SG1312R7N32,

BDE-SG1312R7U0,

BDE-SG1312R7N0,

BDE-SG1312R7U32-IN,

BDE-SG1312R7N32-IN,

BDE-SG1312R7U0-IN,

BDE-SG1312R7N0-IN

BDE-SG1311R3U32,

BDE-SG1311R3N32,

BDE-SG1311R3U0,

BDE-SG1311R3N0

BDE-SG1311R3U32-IN,

BDE-SG1311R3N32-IN,

BDE-SG1311R3U0-IN,

BDE-SG1311R3N0-IN

The differences between series models mainly lie in the size of Flash and SRAM, antenna interface method, whether an external 32Mbit SPI Flash is configured, and differences in operating temperature.

Model	HVIN	External photo difference
BDE-SG1314R10U32, BDE-SG1314R10U0, BDE-SG1314R10U32-IN, BDE-SG1314R10U0-IN,	BDE-SG1314R10U32	
BDE-SG1314R10N32, BDE-SG1314R10N0, BDE-SG1314R10N32-IN, BDE-SG1314R10N0-IN,	BDE-SG1314R10N32	
BDE-SG1312R7U32, BDE-SG1312R7U0, BDE-SG1312R7U32-IN, BDE-SG1312R7U0-IN,	BDE-SG1312R7U32	
BDE-SG1312R7N32, BDE-SG1312R7N0, BDE-SG1312R7N32-IN, BDE-SG1312R7N0-IN,	BDE-SG1312R7N32	
BDE-SG1311R3U32, BDE-SG1311R3U0, BDE-SG1311R3U32-IN, BDE-SG1311R3U0-IN,	BDE-SG1311R3U32	
BDE-SG1311R3N32, BDE-SG1311R3N0, BDE-SG1311R3N32-IN, BDE-SG1311R3N0-IN	BDE-SG1311R3N32	

According to RSP-100 issue 12 Clause 9.3(a) and Clause 9.3(c), we request to certify these HVINs under the New Family Product Certification.

Sincerely,



(Signed)

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